



July 18, 2017

Ms. Susanna Kooistra
Mr. Patrick Merias
3GPP Mobile Competence Centre (ETSI)
650, Route des Lucioles
06921, Sophia Antipolis
FRANCE

Nomination of Mr. Brian Classon for 3GPP RAN WG1 Chairman

Dear Susanna and Patrick,

On behalf of HuaWei Technologies Co., Ltd., a 3GPP member from CCSA, I am pleased to nominate Mr. Brian Classon as candidate for Chairman of 3GPP TSG RAN WG1 in the upcoming election in August 2017. Huawei is committed to the 3GPP standards eco-system towards overall success of wireless communications and will fully support Brian in his chairman role.

Brian has more than 22 years experience in the communication industry and has been working for Huawei for 9 years as the Huawei RAN1 head of delegation. He has solid technical skills in HSPA, LTE and NR, and deep understanding of overall systems aspects from the perspective of both mobile and network sides. Brian has shown strong leadership and has a proven track record on planning work for the WG and driving consensus on contentious issues. He will be strictly impartial and neutral, and will use his skills for consensus building in all the decisions in RAN1. Brian will be looking to grow the industry ecosystem for the benefit of all stakeholders.

Brian is informed about and aware of the antitrust/competition laws and regulations of relevant jurisdictions and shall comply with such laws while acting in his capacity as RAN1 chairman. A brief CV for Brian is attached.

We believe that Brian's experience and technical leadership skills make him highly suitable for the chairman role in TSG RAN WG1 through the challenges of the coming years.

Sincerely Yours,

Wan Lei
Director of Wireless Standards Department
HuaWei Technologies Co., Ltd.

A handwritten signature in black ink that reads "Wan Lei".

HUAWEI
TECHNOLOGIES CO.,LTD.
Huawei Industrial Base,
Bantian Longgang
Shenzhen 518129 P.R.China
Tel: +86 755 28780808



Curriculum Vitae of Mr. Brian Classon

Brian was born and raised in the Washington D.C. area of the USA. He graduated from the University of Maryland at College Park and the University of Illinois at Urbana Champaign, and has focused on communications engineering throughout his career. He worked 13 years with Motorola Labs. After serving as the Motorola Labs global lead for LTE in RAN1, Brian joined Huawei as Huawei RAN1 head of delegation and chief delegate. He has been with Huawei for 9 years.

During his long career, Brian has impacted many commercial systems (EDGE, 1xEV-DO/DV, WiMAX, HSPA, LTE) through innovative research, academic publication, and active attendance and participation in industry standards (3GPP2, 802.16, and 3GPP). He is a Senior Member of the IEEE and a licensed Professional Engineer in the state of Illinois.

Brian contributed to the initial HSPA proposal in 2000, has attended RAN1 continuously since the start of LTE and has been well known in 3GPP since the early time of LTE. He is the current editor for the LTE core specification 3GPP TS 36.212 and the recipient of the 2014 3GPP excellence award. He has chaired sessions in RAN1 on multiple topics, including completing NB-IoT in RAN1#84bis.